

## TECHNICAL CHARACTERISTICS

### 1. General Characteristics

Dimension: 18.80L x 15.85W x 1.70H mm  
 Weight: Approx. 0.63 g  
 Contact principle: Friction technology  
 Operating position: Shaft up / Down / Horizontal  
 Mounting System: SMT Type (without post)  
 Function: With Tray Type (Tray exclude)  
 Durability: 5,000 cycles min.

### 2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0  
 RoHS Directive 2011/65/EU Compliant

### 3. Electrical Characteristics

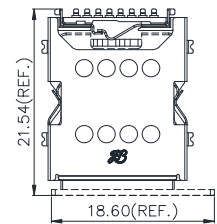
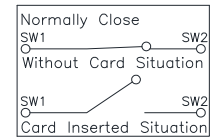
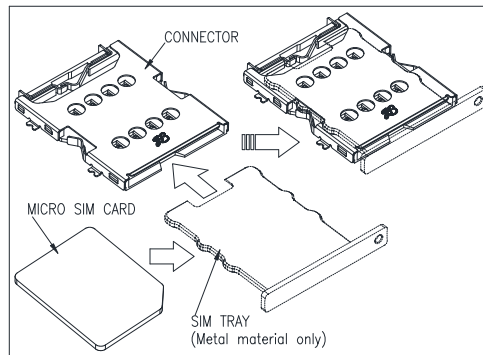
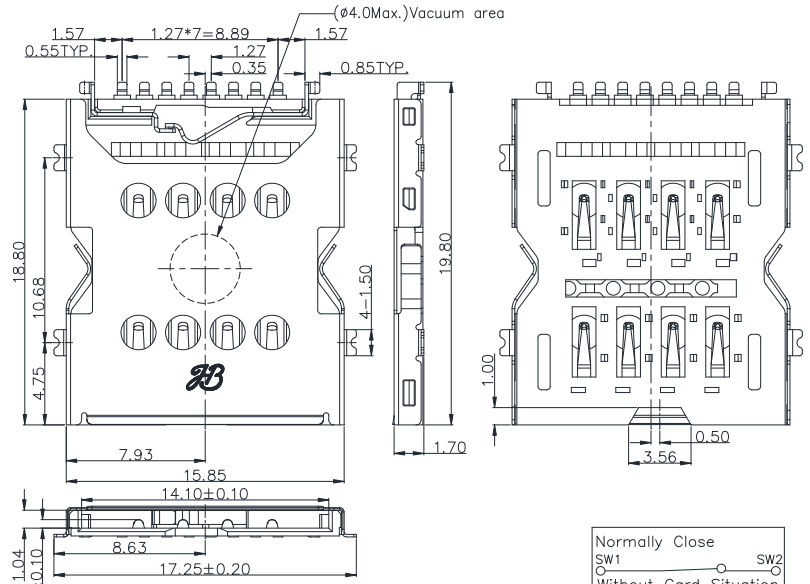
Number of contacts: 8 pins  
 Contact resistance: 50 mΩ typical, 100 mΩ max.  
 Insulation resistance: >1000 MΩ / 500 VDC  
 Switch type: Blade  
 Operation: Normally Close

### 4. Solderability

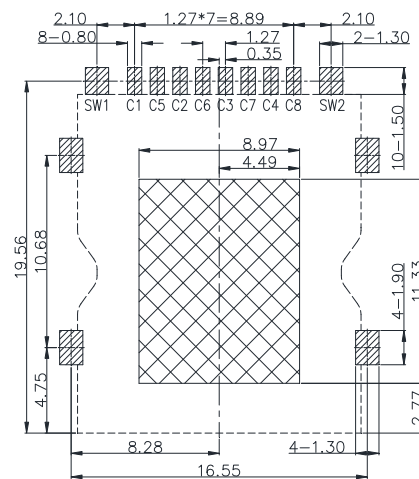
Wave: Not applicable  
 IR reflow: 260°C, 10 sec. Max.  
 Manual soldering: 360°C, 3 sec. Max.

### 5. Environmental Characteristics

Operating temperature: - 40°C ~ + 85°C  
 Operating humidity: 10 % ~ 95 % RH  
 Storage temperature: - 40°C ~ + 85°C  
 Storage humidity: 10 % ~ 95 % RH



Unit: mm; Tolerances: ±0.15 mm  
 Mechanical outline dimension



▨ BOARD PAD    ▩ NO WIRING AREA

Unit: mm; Tolerances: ±0.05 mm  
 Reference dimension for PCB layout

HB Micro SIM Card Connector

Model No.: ICC-M03

Revision: 1.2

Date: OCT. 25, 2019

Note:

1. Coplanarity of solder pins 0.10mm max.
2. Recommended thickness of solder paste > 0.15mm.